L Number	Hits	Search Text	DB	Time stamp
	8421	encapsul\$ and metal and (pcb or (printed	USPAT;	2004/06/23 16:05
		adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	}
	E040	oncency of and metal and (not or (printed	USPAT;	2004/06/23 16:03
-	5948	encapsul\$ and metal and (pcb or (printed	•	2004/06/23 16:03
		adj circuit adj board)) and substrate	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	290	encapsul\$ and (metal adj sheets) and (pcb	USPAT;	2004/06/23 14:55
		or (printed adj circuit adj board)) and	US-PGPUB;	
		substrate	EPO; JPO;	
1			DERWENT;	
		·	IBM TDB	-
_	402	encapsul\$ and (metal adj plates) and (pcb	USPĀT;	2004/06/23 15:27
	102	or (printed adj circuit adj board)) and	US-PGPUB;	
		substrate	EPO; JPO;	
		Substrate		
			DERWENT;	
			IBM_TDB	0004/06/00 15 44
-	96	(encapsul\$ with (metal adj layers)) and	USPAT;	2004/06/23 15:44
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
		and substrate	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	12	(encapsul\$ with (metal adj films)) and	USPAT;	2004/06/23 15:36
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
		and substrate	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	١ ,	/	USPAT;	2004/06/23 15:37
_	2	(encapsul\$ with (metal adj regions)) and		2004/06/23 15:3/
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
		and substrate	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	6	(encapsul\$ with (metal adj portions)) and	USPAT;	2004/06/23 15:40
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
		and substrate	EPO; JPO;	
			DERWENT;	
1			IBM TDB	
_	18	(encapsul\$ with (metal adj lines)) and	USPAT;	2004/06/23 15:41
	1	(pcb or (printed adj circuit adj board))	US-PGPUB;	
		and substrate	EPO; JPO;	
		and substrace	DERWENT;	[
1			IBM TDB	
1		C400572 mm		2004/06/23 16:03
-	2	6489572.pn.	USPĀT;	2004/00/23 10:03
			US-PGPUB;	!
			EPO; JPO;	
1			DERWENT;	
1			IBM_TDB	
-	887	encapsul\$ and metal and (pcb or (printed	USPAT;	2004/06/23 16:07
		adj circuit adj board)) and (injection adj	US-PGPUB;	
		molding)	EPO; JPO;	1
1			DERWENT;	
1			IBM TDB	
_	726	encapsul\$ and metal and (pcb or (printed	USPAT;	2004/06/23 16:09
	'25	adj circuit adj board)) and (injection adj	US-PGPUB;	
1		molding) and plastic	EPO; JPO;	
1		moraring/ and prasere	DERWENT;	
			IBM TDB	
	.			2004/06/22 16-02
-	1	encapsul\$ and metal and (pcb or (printed	USPAT;	2004/06/23 16:08
1		adj circuit adj board)) and (injection adj	US-PGPUB;	
		molding) and plastic and (middle adj	EPO; JPO;	
		board)	DERWENT;	
			IBM_TDB	
-	3		USPĀT;	2004/06/23 16:56
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
		and substrate	EPO; JPO;	
			DERWENT;	
			IBM TDB	1
L	L		1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	l

Search History 6/24/04 8:23:22 AM Page 1

- 2 (counterdoped adj collector) with (buried USPAT; us-pgpuB; EPO; JPO; DERWENT; IBM TDB	2004/06/23 16:21
EPO; JPO; DERWENT;	
DERWENT;	
IBM TDB	
- 1 (counter adj doped adj collector) with USPAT; (buried adj collector) US-PGPUB;	2004/06/23 16:22
(buried adj collector) US-PGPUB; EPO; JPO;	
DERWENT;	
IBM_TDB	0004/05/00 45 00
- 0 (double adj doped adj collector) with USPAT; US-PGPUB;	2004/06/23 16:23
(buried adj coffector) US-FGFOB, EPO; JPO;	
DERWENT;	İ
IBM_TDB	0004/06/00 16 00
- 0 (double adj diffused adj collector) with USPAT; (buried adj collector) US-PGPUB;	2004/06/23 16:23
EPO; JPO;	
DERWENT;	
IBM_TDB	0004/06/02 16:02
- 0 (double adj implanted adj collector) with USPAT; (buried adj collector) US-PGPUB;	2004/06/23 16:23
EPO; JPO;	
DERWENT;	
IBM_TDB	2004/06/22 16:22
- 0 (double adj dopant adj collector) with USPAT; (buried adj collector) US-PGPUB;	2004/06/23 16:23
EPO; JPO;	
DERWENT;	
IBM_TDB	2004/06/22 16.25
- 0 (double adj diffusion adj collector) with USPAT; (buried adj collector) US-PGPUB;	2004/06/23 16:25
EPO; JPO;	
DERWENT;	
IBM_TDB USPAT;	2004/06/23 16:42
- 219 double adj collectors USPAT; US-PGPUB;	2004/06/23 16:42
EPO; JPO;	
DERWENT;	
	2004/06/23 16:43
US-PGPUB;	2004/00/25 10.45
EPO; JPO;	
DERWENT;	
	2004/06/23 16:57
US-PGPUB;	
EPO; JPO;	
DERWENT; IBM TDB	
- 41 (encapsulated adj metal) and (pcb or USPAT;	2004/06/23 17:01
(printed adj circuit adj board)) US-PGPUB;	
EPO; JPO;	
DERWENT; IBM TDB	
- 4 (encapsulated adj foil) and (pcb or USPAT;	2004/06/23 17:02
(printed adj circuit adj board)) US-PGPUB;	
EPO; JPO;	
DERWENT; IBM TDB	
- 7 (encapsulated adj metallic) and (pcb or USPAT;	2004/06/23 17:06
(printed adj circuit adj board)) US-PGPUB;	
EPO; JPO;	
реголиме.	
DERWENT;	
IBM_TDB	2004/06/23 17:28
IBM_TDB	2004/06/23 17:28
IBM_TDB	2004/06/23 17:28

Search History 6/24/04 8:23:22 AM Page 2

. Ša				
_	144	257/709.ccls.	USPAT;	2004/06/23 17:32
ļ			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
i			IBM_TDB	
-	429	257/710.ccls.	USPAT;	2004/06/23 17:42
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1	050/044	IBM_TDB	0004/06/02 17:51
-	154	257/711.ccls.	USPAT;	2004/06/23 17:51
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	100	257/6001-	IBM_TDB USPAT;	2004/06/23 18:29
-	182	257/699.ccls.	US-PGPUB;	2004/06/23 18:29
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1275	(lga or (land adj grid adj array)) and	USPAT;	2004/06/23 18:48
	12/3	(pcb or (printed adj circuit adj board))	US-PGPUB;	2004/00/25 10:40
		t the princed and circuit and board,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	252	(substrate with (metal adj sheets)) and	USPAT;	2004/06/23 18:56
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
		(For or (Formore any research any research)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	18	(substrate with (metal adj lands)) and	USPĀT;	2004/06/23 20:19
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	42		USPAT;	2004/06/23 19:00
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		l , , , , , , , , , , , , , , , , , , ,	IBM_TDB	0004/06/00 10 06
-	92		USPAT;	2004/06/23 19:06
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	160	(substrate with (metal adj strips)) and	USPAT;	2004/06/23 19:12
	100	(pcb or (printed adj circuit adj board))	US-PGPUB;	2004/00/23 13:12
1		(peb of (princed day effecte day board))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	369	(substrate with (metal adj (films or	USPĀT;	2004/06/23 20:04
		layers))) with (pcb or (printed adj	US-PGPUB;	
		circuit adj board))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18		USPAT;	2004/06/23 20:07
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
1 -	1 112	/ (cubetrate with (motal add plates)) with	TICDATE.	1 2004/06/23 20:09

(substrate with (metal adj plates)) with

(pcb or (printed adj circuit adj board))

(substrate with (contductive adj lands))
and (pcb or (printed adj circuit adj

2004/06/23 20:08

2004/06/23 20:29

USPĀT;

USPAT; US-PGPUB;

EPO; JPO; DERWENT; IBM TDB

US-PGPUB; EPO; JPO; DERWENT; IBM TDB

Search History 6/24/04 8:23:22 AM Page 3

board))

	100		Transm.	0004/06/02 20 24
-	128		USPAT;	2004/06/23 20:24
		and (pcb or (printed adj circuit adj	US-PGPUB;	
		board))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	484	(====================================	USPAT;	2004/06/23 20:25
		and (pcb or (printed adj circuit adj	US-PGPUB;	
		board))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	33	substrate near (pcb or (printed adj	USPAT;	2004/06/23 20:27
		circuit adj board)) near array	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	(substrate with (metal adj array)) and	USPAT;	2004/06/23 20:30
	Ĭ	(pcb or (printed adj circuit adj board))	US-PGPUB;	2001,00,20 20.00
		(peb of (princed ad) circuit adj board)	EPO; JPO;	
			DERWENT;	
			1	
	_	(IBM_TDB	2004/06/23 20:30
_	0	(000000000 00000 (000000 000) 000000 (00000000	USPAT;	2004/06/23 20:30
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	(substrate and (metal adj array)) and (pcb	USPAT;	2004/06/23 20:31
		or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	:
			DERWENT;	
			IBM_TDB	
-	204		USPAT;	2004/06/23 20:43
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	12	(metal adj array) and (pcb or (printed adj	USPAT;	2004/06/23 20:46
		circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	5	(metal adj sheet adj array) and (pcb or	USPĀT;	2004/06/23 20:47
ļ	Ĭ	(printed adj circuit adj board))	US-PGPUB;	=====================================
		1	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	10	metal adj sheet adj array	USPĀT;	2004/06/23 20:48
	19	i sineet daj array	US-PGPUB;	2007/00/25 20.40
	ļ		EPO; JPO;	
			DERWENT;	
			IBM TDB	
	105	matal add (mlata am line am atain am line)	USPAT;	2004/06/23 20:49
-	125	1		2004/06/23 20:49
		adj array	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
L	L <u>.</u>		IBM_TDB	

Search History 6/24/04 8:23:22 AM Page 4

L Number	Hits	Search Text	DB	Time stamp
1	2	6489572.pn.	USPAT;	2004/06/24 15:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		C400570	IBM_TDB	2004/06/24 15:45
2	1	6489572.pn. and plastic	USPAT;	2004/06/24 15:45
			US-PGPUB; EPO; JPO;]
			DERWENT;	
		,	IBM TDB	
3	0	6489572.pn. and industrial	USPAT;	2004/06/24 15:45
		o cosoverp and anador-a-	US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	0	6489572.pn. and injection	USPAT;	2004/06/24 15:45
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
ا د	100		IBM_TDB	2004/06/24 15:50
5	108	stacked adj metal adj sheets	USPAT;	2004/06/24 15:58
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
6	351	257/798.ccls.	USPAT;	2004/06/24 16:25
	331	1 , , , , , , , , , , , , , , , , ,	US-PGPUB;	-551,55,21 15.25
			EPO; JPO;]
			DERWENT;	1
			IBM_TDB	
7	0	(substrate adj structure) and (middle adj	USPĀT;	2004/06/24 16:42
		board)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2.4	() () () () () () () () () ()	IBM_TDB	0004/06/04 16:46
8	34	, , , , , , ,	USPAT;	2004/06/24 16:46
		board)	US-PGPUB; EPO; JPO;	
			DERWENT;	
		·	IBM TDB	
9	1	(substrate adj structure) and (center adj	USPAT;	2004/06/24 16:47
-	_	board)	US-PGPUB;	}
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	5	(tab or (tape adj automated adj bonding))	USPAT;	2004/06/24 16:50
		and stacked and encapsula\$ and ((middle or	US-PGPUB;	
		center) adj board)	EPO; JPO;	
			DERWENT; IBM TDB	
12	228	((middle or center) adj board) and package	USPAT;	2004/06/24 16:50
**	220	((minding of center) adj board) and package	US-PGPUB;	2007/00/24 10:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	7	(tab or (tape adj automated adj bonding))	USPĀT;	2004/06/24 15:03
		and stacked and multilayer and encapsula\$	US-PGPUB;	
		and leadless and (flip adj chip)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	10	(tab or (tape adj automated adj bonding))	USPAT;	2004/06/24 15:04
		and stacked and multilayer and encapsula\$	US-PGPUB;	
		and leadless	EPO; JPO;	
			DERWENT;	
_	47	(tab or (tabe add automated add bording))	IBM_TDB USPAT;	2004/06/24 15:04
-	4.7	<pre>(tab or (tape adj automated adj bonding)) and stacked and encapsula\$ and leadless</pre>	USPAT; US-PGPUB;	2004/00/24 15:04
		and sedened and encapsuray and readless	EPO; JPO;	
			DERWENT;	
: !			IBM TDB	1

-	1696	(tab or (tape adj automated adj bonding))	USPAT;	2004/06/24 16:48
		and stacked and encapsula\$	US-PGPUB;	
			EPO; JPO;	
}			DERWENT;	ŀ
•			IBM_TDB	
i –	404	257/787.ccls. and metal and (pcb or	USPAT;	2004/06/24 15:07
		(printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	308	257/787.ccls. and metal and substrate and	USPAT;	2004/06/24 15:08
		(pcb or (printed adj circuit adj board))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

Page 2